



FMS6203

Low-Cost 3-Channel Video Filter Driver for SD/PS/HD

Features

- Three 6th-Order Video Anti-Aliasing or Reconstruction Filters
- Supports Component YPrPb or RGB Video
- Three Channels, Selectable to 8MHz, 16MHz, 32MHz for SD/PS/HD Applications
- Includes Wide Bandwidth Bypass Mode
- 6dB Gain Option Available for 150Ω Double Terminated Video Load
- 0dB Gain Option Available for High Impedance Loading
- Selectable Clamp or Bias Mode on Pb,Pr / B,R Inputs
- Inputs and Outputs can be either AC or DC Coupled
- DC-Coupled Outputs Eliminate Expensive Coupling Capacitors
- Output Disable
- Single 5V supply
- 2kV CDM / 8kV HBM ESD Protection
- Lead-Free TSSOP-14 Package

Description

The FMS6203 offers comprehensive filtering for set-top box or DVD applications. It is intended to replace passive LC filters and drivers with a low-cost integrated device.

Filter channels are specialized for either component (YPbPr) or RGB video signals. These channels offer a selectable frequency response of 8, 16, or 32MHz. The filters can also be bypassed for high-frequency operation. Additional functionality of these channels includes input biasing mode and output disable.

The FMS6203 may be driven directly by a DC-coupled DAC output or an AC-coupled signal. All inputs accept standard 1V_{pp} video signals.

Each channel includes an output amplifier capable of driving a single (150Ω) AC- or DC-coupled video load. All outputs can be disabled to save power in DC-coupled applications.

The device is available in two factory-set options, a 0dB gain option and a 6dB gain option.

Applications

- Cable and Satellite Set-Top Boxes
- DVD Players
- HDTV
- Personal Video Recorders (PVR)
- Video On Demand (VOD)

Functional Block Diagram

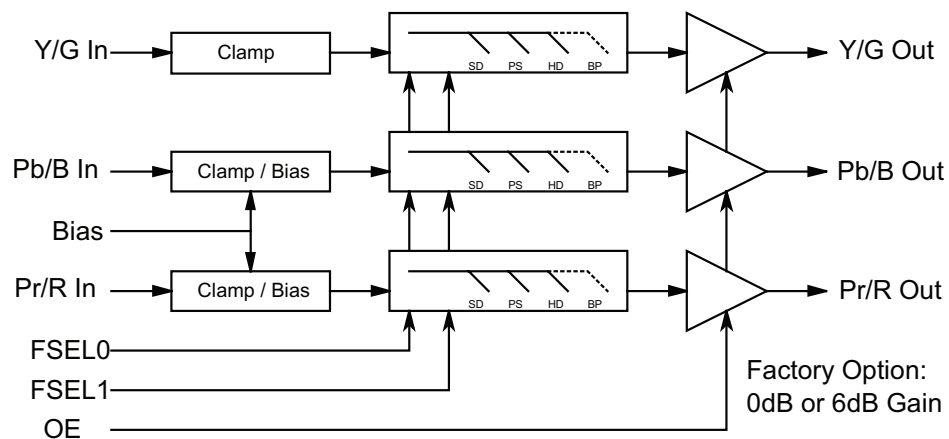


Figure 1. Block Diagram

Ordering Information

Part Number	Gain Setting	Package	Pb-Free	Operating Temperature Range	Packing Method
FMS6203MTC1400	0dB	TSSOP-14	Yes	-40°C to 85°C	Tube
FMS6203MTC1400X	0dB	TSSOP-14	Yes	-40°C to 85°C	Tape and Reel
FMS6203MTC1406	6dB	TSSOP-14	Yes	-40°C to 85°C	Tube
FMS6203MTC1406X	6dB	TSSOP-14	Yes	-40°C to 85°C	Tape and Reel

Note:

- Moisture sensitivity level for all parts is MSL-1.

Pin Configuration

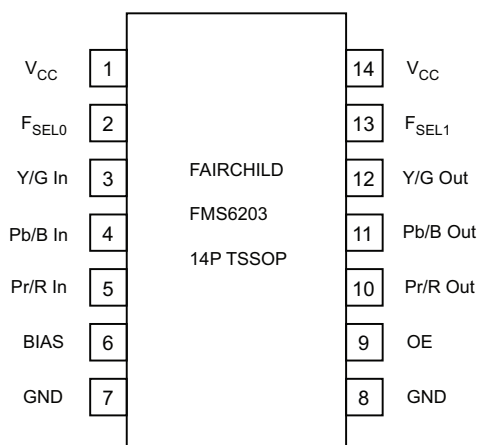


Figure 2. Pin Configuration

Pin Assignments

Pin #	Name	Type	Description
1	V _{CC}	Input	+5V supply.
2	F _{SEL0}	Input	Selects filter corner frequency.
3	Y/G In	Input	Selectable video input.
4	Pb/B In	Input	Selectable video input.
5	Pr/R In	Input	Selectable video input.
6	BIAS	Input	Input Bias on Pb/B Pr/R 0 = Bias 1 = Clamp.
7	GND	Input	Must be tied to ground. Do not float.
8	GND	Input	Must be tied to ground. Do not float.
9	OE	Input	Output disable control 0 = OFF 1 = ON.
10	Pr/R Out	Output	Filtered SD,PS,HD,BP video output.
11	Pb/B Out	Output	Filtered SD,PS,HD,BP video output.
12	Y/G Out	Output	Filtered SD,PS,HD,BP video output.
13	F _{SEL1}	Input	Selects filter corner frequency.
14	V _{CC}	Input	+5V supply.

Absolute Maximum Ratings

The “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The “Recommended Operating Conditions” table defines the conditions for actual device operation.

Parameter	Min.	Max.	Unit
DC Supply Voltage	-0.3	6	V
Analog and Digital I/O	-0.3	$V_{CC} + 0.3$	V
Output Current, Any One Channel, Do Not Exceed		50	mA

Reliability Information

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_J	Junction Temperature			150	°C
T_{STG}	Storage Temperature Range	-65		150	°C
T_L	Lead Temperature, Soldering 10 seconds			300	°C
Θ_{JA}	Thermal Resistance JEDEC Standard Multi-Layer Test Boards, Still Air		97		°C/W

Recommended Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
T_A	Operating Temperature Range	-40		85	°C
V_{CC}	Supply Voltage Range	4.75	5.0	5.25	V

DC Electrical Characteristics

$T_A = 25^\circ\text{C}$, $V_{CC} = 5\text{V}$, $R_{\text{source}} = 37.5\Omega$, inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz; all gain options; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
I_{CC}	Supply Current ⁽¹⁾	No Load		36	75	mA
I_{CC1}	Supply Current ⁽¹⁾	No Load, Output Disabled		15	35	mA
V_{IN}	Video Input Voltage Range	Referenced to GND if DC Coupled		1.0		V_{pp}
V_{IL}	Digital Input Low ⁽¹⁾	F_{SEL0}, F_{SEL1}	0		0.8	V
V_{IH}	Digital Input High ⁽¹⁾	F_{SEL0}, F_{SEL1}	2.4		V_{CC}	V
t_{ENABLE}	Output Enable Time	150Ω DC load		300		ns

Note:

1. 100% tested at 25°C .

Standard Definition Electrical Characteristics

$T_A = 25^\circ\text{C}$, $V_{IN} = 1V_{pp}$, $V_{CC} = 5\text{V}$, $R_{\text{source}} = 37.5\Omega$, all inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz, all gain options; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
AV_{SD}	Channel Gain Error ⁽¹⁾		-0.4	0	0.4	dB
f_{1dBSD}	-1dB Bandwidth ⁽¹⁾		5.20	7.15		MHz
f_{cSD}	-3dB Bandwidth			8		MHz
f_{SBSD}	Attenuation (Stopband Reject) ⁽¹⁾	$f = 27\text{MHz}$	40	50		dB
DG	Differential Gain			0.3		%
DP	Differential Phase			1.0		°
THD	Total Harmonic Distortion, Output	$V_{OUT} = 1.4V_{pp}$, 3.58MHz		0.6		%
X_{TALKSD}	Crosstalk (ch-to-ch)	1MHz		-70		dB
SNR	Signal-to-Noise Ratio ⁽²⁾	NTC-7 weighting, 100kHz to 4.2MHz		75		dB
t_{pdSD}	Propagation Delay	Delay from input to output, 4.5MHz		85		ns

Notes:

1. 100% tested at 25°C .
2. $SNR = 20 * \log(714\text{mV} / \text{rms noise})$.

Progressive Scan Electrical Characteristics

$T_A = 25^\circ\text{C}$, $V_{IN} = 1V_{pp}$, $V_{CC} = 5V$, $R_{Source} = 37.5\Omega$, all inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz, all gain options; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
AV_{PS}	Channel Gain Error ⁽¹⁾		-0.4	0	0.4	dB
f_{1dBPS}	-1dB Bandwidth ⁽¹⁾		10.0	13.5		MHz
f_{cPS}	-3dB Bandwidth			16		MHz
f_{SBPS}	Attenuation (Stopband Reject) ⁽¹⁾	$f = 54\text{MHz}$	37	44		dB
THD	Total Harmonic Distortion, Output	$V_{OUT} = 1.4V_{pp}$, 7MHz		0.55		%
X_{TALKPS}	Crosstalk (ch-to-ch)	1MHz		-75		dB
SNR	Signal-to-Noise Ratio ⁽²⁾	Unweighted; 100kHz to 15MHz		66		dB
t_{pdPS}	Propagation Delay	Delay from input to output, 10MHz		47		ns

Notes:

- 100% tested at 25°C .
- $SNR = 20 * \log(714\text{mV} / \text{rms noise})$.

High-Definition Electrical Characteristic

$T_A = 25^\circ\text{C}$, $V_{IN} = 1V_{pp}$, $V_{CC} = 5V$, $R_{Source} = 37.5\Omega$, all inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz, all gain options; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
AV_{HD}	Channel Gain Error ⁽¹⁾		-0.4	0	0.4	dB
f_{1dBHD}	-1dB Bandwidth ⁽¹⁾		28	31		MHz
f_{cHD}	-3dB Bandwidth			32		MHz
f_{SBHD}	Attenuation (Stopband Reject) ⁽¹⁾	$f = 74.25\text{MHz}$	30	40		dB
THD	Total Harmonic Distortion, Output	$V_{OUT} = 0.7V_{pp}$, 22MHz, 0dB, 10k Ω load		0.5		%
		$V_{OUT} = 1.4V_{pp}$, 22MHz, 6dB, 150 Ω load		0.5		%
X_{TALKHD}	Crosstalk (ch-to-ch)	1MHz		-75		dB
		30MHz		-57		dB
SNR	Signal-to-Noise Ratio ⁽²⁾	Unweighted, 100kHz to 30MHz		66		dB
t_{pdHD}	Propagation Delay	Delay from input to output, 20MHz		25		ns

Notes:

- 100% tested at 25°C .
- $SNR = 20 * \log(714\text{mV} / \text{rms noise})$.

Bypass Mode Electrical Characteristics

$T_A = 25^\circ\text{C}$, $V_{IN} = 1V_{pp}$, $V_{CC} = 5V$, $R_{source} = 37.5\Omega$, all inputs AC coupled with $0.1\mu\text{F}$, all outputs AC coupled with $220\mu\text{F}$ into 150Ω loads, referenced to 400kHz, all gain options; unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
AV_{BP}	Channel Gain Error ⁽¹⁾	DC	-0.4	0	0.4	dB
$f_{1dB BP}$	-1dB Bandwidth			90		MHz
$f_{3dB BP}$	-3dB Bandwidth			115		MHz
THD	Total Harmonic Distortion, Output	$V_{OUT} = 0.7V_{pp}$, 22MHz, 0dB, 10k Ω load		0.3		%
		$V_{OUT} = 1.4V_{pp}$, 22MHz, 6dB, 150 Ω load		0.25		%
X_{TALKBP}	Crosstalk (ch-to-ch)	1MHz		-74		dB
		30MHz		-64		dB
SNR	Signal-to-Noise Ratio ⁽²⁾	Unweighted, 100kHz to 30MHz		70		dB

Notes:

- 100% tested at 25°C.
- SNR = 20 * log (714mV / rms noise).

Frequency Select Truth Table

F_{SEL1}	F_{SEL0}	Filter Frequency	Video Format	Sync Format
0	0	8MHz	SD,480i	Bi-level, 4.7 μs pulse width
0	1	16MHz	PS,480p	Bi-level, 2.35 μs pulse width
1	0	32MHz	HD,1080i,720p	Tri-level, 589ns pulse width
1	1	Bypass		

Layout Considerations

General layout and supply bypassing play a major role in high-frequency performance and thermal characteristics. Fairchild offers a demonstration board to guide layout and aid device evaluation. The demo board is a four-layer board with full power and ground planes. Following this layout configuration provides optimum performance and thermal characteristics for the device. For the best results, follow the steps and recommended routing rules listed below.

Recommended Routing/Layout Rules

- Do not run analog and digital signals in parallel.
- Use separate analog and digital power planes to supply power.
- Traces should run on top of the ground plane at all times.
- No trace should run over ground/power splits.
- Avoid routing at 90-degree angles.
- Minimize clock and video data trace length differences.
- Include 10 μ F and 0.1 μ F ceramic power supply bypass capacitors.
- Place the 0.1 μ F capacitor within 0.1 inches of the device power pin.
- Place the 10 μ F capacitor within 0.75 inches of the device power pin.
- For multilayer boards, use a large ground plane to help dissipate heat.

- For two-layer boards, use a ground plane that extends beyond the device body by at least 0.5 inches on all sides. Include a metal paddle under the device on the top layer.
- Minimize all trace lengths to reduce series inductance.

Thermal Considerations

Since the interior of most systems, such as set-top-boxes, TVs, and DVD players are at +70°C; consideration must be given to providing an adequate heat sink for the device package for maximum heat dissipation. When designing a system board, determine how much power each device dissipates. Ensure that devices of high power are not placed in the same location, such as directly above (top plane) and below bottom plane) each other on the PCB.

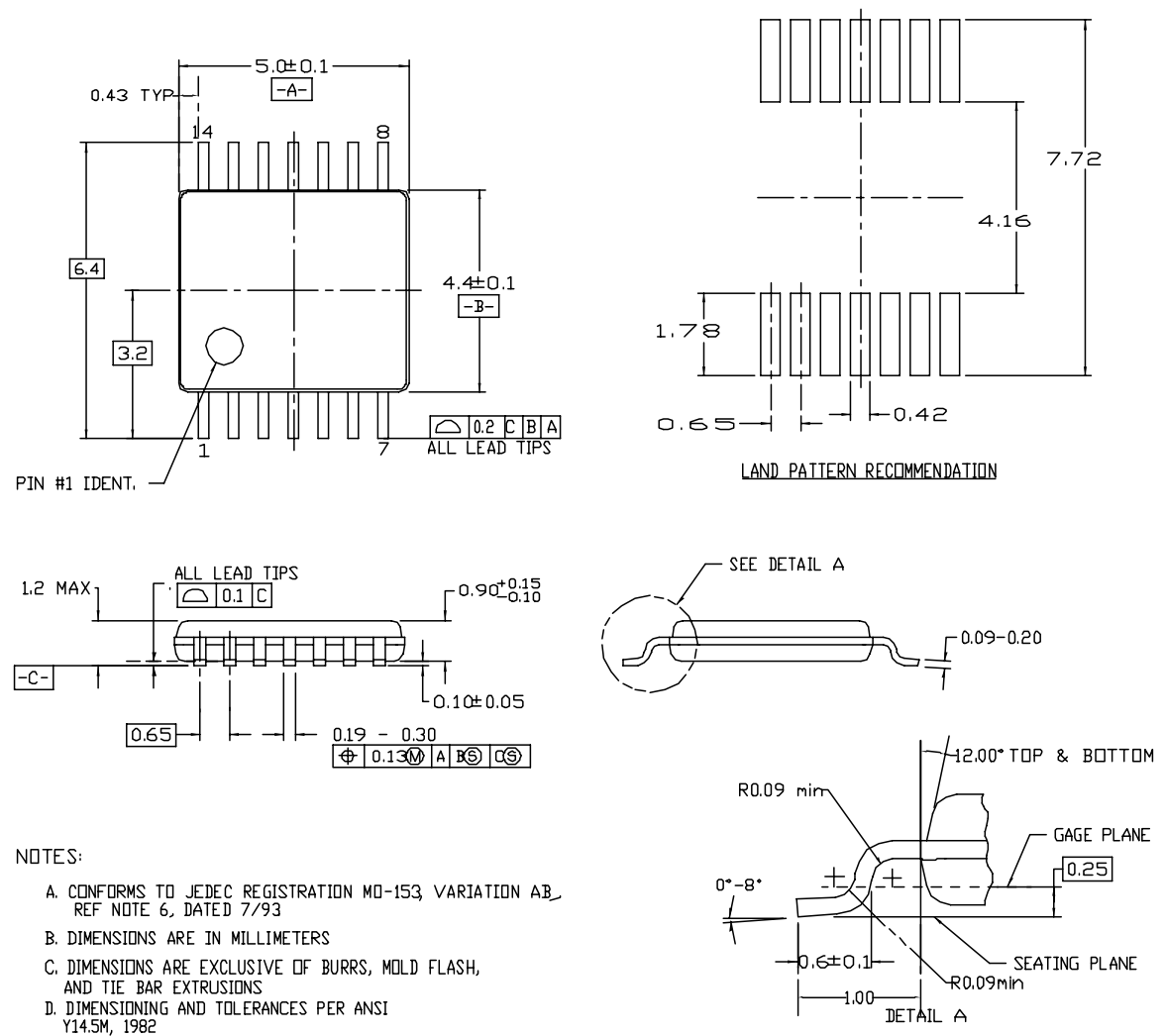
PCB Thermal Layout Considerations

- Understand the system power requirements and environmental conditions.
- Maximize thermal performance of the PCB.
- Consider using 70 μ m of copper for high-power designs.
- Make the PCB as thin as possible by reducing FR4 thickness.
- Use vias in power pad to tie adjacent layers together.
- Remember that baseline temperature is a function of board area, not copper thickness.
- Modeling techniques can provide a first-order approxi-

Mechanical Dimensions

Dimensions are in millimeters unless otherwise noted.

14-Lead TSSOP



- NOTES:
- CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93
 - DIMENSIONS ARE IN MILLIMETERS
 - DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP)

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACE ^x TM	FACT Quiet Series TM	OCX TM	SILENT SWITCHER [®]	UniFET TM
ActiveArray TM	GlobalOptoisolator TM	OCXPro TM	SMART START TM	UltraFET [®]
Bottomless TM	GTO TM	OPTOLOGIC [®]	SPM TM	VCX TM
Build it Now TM	HiSeC TM	OPTOPLANAR TM	Stealth TM	Wire TM
CoolFET TM	I ² C TM	PACMAN TM	SuperFET TM	
CROSSVOLT TM	i-Lo TM	POP TM	SuperSOT TM _3	
DOME TM	ImpliedDisconnect TM	Power247 TM	SuperSOT TM _6	
EcoSPARK TM	IntelliMAX TM	PowerEdge TM	SuperSOT TM _8	
E ² CMOS TM	ISOPLANAR TM	PowerSaver TM	SyncFET TM	
EnSigna TM	LittleFET TM	PowerTrench [®]	TCM TM	
FACT [®]	MICROCOUPLER TM	QFET [®]	TinyBoost TM	
FAST [®]	MicroFET TM	QS TM	TinyBuck TM	
FASTr TM	MicroPak TM	QT Optoelectronics TM	TinyPWM TM	
FPS TM	MICROWIRE TM	Quiet Series TM	TinyPower TM	
FRFET TM	MSX TM	RapidConfigure TM	TinyLogic [®]	
	MSXPro TM	RapidConnect TM	TINYOPTO TM	
Across the board. Around the world. TM		μSerDes TM	TruTranslation TM	
The Power Franchise [®]		ScalarPump TM	UHC [®]	
Programmable Active Droop TM				

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

Rev. I21